



N-Channel Depletion-Mode Vertical DMOS FETs

Ordering Information

BV _{DSX} / BV _{DGX}	R _{DS(ON)} (max)	I _{DSS} (min)	Order Number / Package	
			TO-92	DIE
400V	6.0Ω	300mA	DN2640N3	DN2640ND

Features

- High input impedance
- Low input capacitance
- Fast switching speeds
- Low on resistance
- Free from secondary breakdown
- Low input and output leakage

Applications

- Normally-on switches
- Solid state relays
- Converters
- Linear amplifiers
- Constant current sources
- Power supply circuits
- Telecom

Absolute Maximum Ratings

Drain-to-Source Voltage	BV _{DSX}
Drain-to-Gate Voltage	BV _{DGX}
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

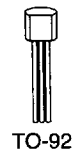
* Distance of 1.6 mm from case for 10 seconds.

Advanced DMOS Technology

These depletion-mode (normally-on) transistors utilize an advanced vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Options



Note: See package outline section for dimensions.

Thermal Characteristics

Package	I _D (continuous)*	I _D (pulsed)	Power Dissipation @ T _C = 25°C	θ _{JC} °C/W	θ _{JA} °C/W	I _{DR} *	I _{DRM}
TO-92	250mA	600mA	1.0W	125	170	250mA	600mA

* I_D (continuous) is limited by max rated T_r

Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter	Min	Typ	Max	Unit	Conditions
BV _{DSX}	Drain-to-Source Breakdown Voltage	400			V	V _{GS} = -6.5V, I _D = 1.0mA
V _{GS(OFF)}	Gate-to-Source OFF Voltage	-1.0		-5.0	V	V _{DS} = 25V, I _D = 1.0mA
ΔV _{GS(OFF)}	Change in V _{GS(OFF)} with Temperature			4.5	mV/°C	V _{DS} = 25V, I _D = 10μA
I _{GSS}	Gate Body Leakage Current			100	nA	V _{GS} = ± 20V, V _{DS} = 0V
I _{D(OFF)}	Drain-to-Source Leakage Current			1.0	μA	V _{GS} = -10V, V _{DS} = Max Rating
				1.0	mA	V _{GS} = -10V, V _{DS} = 0.8 Max Rating T _A = 125°C
I _{DSS}	Saturated Drain-to-Source Current	300			mA	V _{GS} = 0V, V _{DS} = 25V
R _{DS(ON)}	Static Drain-to-Source ON-State Resistance			6.0	Ω	V _{GS} = 0V, I _D = 150mA
ΔR _{DS(ON)}	Change in R _{DS(ON)} with Temperature			1.1	%/°C	V _{GS} = 0V, I _D = 150mA
G _{FS}	Forward Transconductance	300			mS	I _D = 200mA, V _{DS} = 10V
C _{ISS}	Input Capacitance			750	pF	V _{GS} = -10V, V _{DS} = 25V f = 1 MHz
C _{OSS}	Common Source Output Capacitance			75		
C _{RSS}	Reverse Transfer Capacitance			15		
t _{d(ON)}	Turn-ON Delay Time			15	ns	V _{DD} = 25V, I _D = 200mA, R _{GEN} = 10Ω
t _r	Rise Time			20		
t _{d(OFF)}	Turn-OFF Delay Time			25		
t _f	Fall Time			25		
V _{SD}	Diode Forward Voltage Drop			1.8	V	V _{GS} = -10V, I _{SD} = 200mA
t _{rr}	Reverse Recovery Time		800		ns	V _{GS} = -10V, I _{SD} = 1.0A

Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300μs pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

Switching Waveforms and Test Circuit

